

Durethan® BKV25H3.0

PA6-GF25

25% Glass Fiber Reinforced, Injection Molding, Heat Stabilized

Print Date: 2025-09-06

PROPERTIES	TYPICAL DATA	UNIT	TEST METHOD
RHEOLOGICAL PROPERTIES	DRY / COND		
Molding shrinkage (parallel)	0.3 / *	%	ISO 294-4
Molding shrinkage (normal)	0.7 / *	%	ISO 294-4
MECHANICAL PROPERTIES	DRY / COND		
Tensile modulus	8400 / 5500	MPa	ISO 527-1/-2
Stress at break	160 / 100	MPa	ISO 527-1/-2
Strain at break	3.5 / 8	%	ISO 527-1/-2
Flexural modulus	8000 / 4400	MPa	ISO 178
Flexural strength	255 / 150	MPa	ISO 178
Charpy impact strength (+23°C)	70 / 90	kJ/m²	ISO 179/1eU
Charpy impact strength (-30°C)	60 / 50	kJ/m²	ISO 179/1eU
Charpy notched impact strength (+23°C)	12 / 20	kJ/m²	ISO 179/1eA
Charpy notched impact strength (-30°C)	10 / 10	kJ/m²	ISO 179/1eA
Izod notched impact strength (+23°C)	10 / 20	kJ/m²	ISO 180/1A
THERMAL PROPERTIES	DRY / COND		
Melting temperature (10°C/min)	220 / *	°C	ISO 11357-1/-3
Temp. of deflection under load (1.80 MPa)	200 / *	°C	ISO 75-1/-2
Temp. of deflection under load (0.45 MPa)	200 / *	°C	ISO 75-1/-2
Coeff. of linear therm. expansion (parallel)	0.3 / *	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.8 / *	E-4/°C	ISO 11359-1/-2
Burning Behav. at 1.5 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	IEC 60695-11-10

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Property Data

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Burning Behav. at 3.0 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	3/*	mm	IEC 60695-11-10
Burning Behav. at 0.75 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	0.75 / *	mm	IEC 60695-11-10
ELECTRICAL PROPERTIES	DRY / COND		
Relative permittivity (100Hz)	3.5 / 14		IEC 62631-2-1
Relative permittivity (1 MHz)	3.3 / 4.5	_	IEC 62631-2-1
Dissipation factor (100 Hz)	50 / 3000	E-4	IEC 62631-2-1
Dissipation factor (1 MHz)	150 / 1200	E-4	IEC 62631-2-1
Volume resistivity	1E13 / 1E12	Ohm*m	IEC 62631-3-1
Surface resistivity	- / 1E14	Ohm	IEC 62631-3-2
Comparative tracking index	550 / –	V	IEC 60112
OTHER PROPERTIES	DRY / COND		
Water absorption	7 / *	%	Sim. to ISO 62
Humidity absorption	2/*	%	Sim. to ISO 62
Density	1310 / –	kg/m³	ISO 1183
PROCESSING RECOMMENDATIONS	VALUE		
Drying temperature dry air dryer	80	°C	
Drying time dry air dryer	2–6	h	
Residual moisture content	0.03-0.12	%	acc. to Karl Fischer
Melt temperature (Tmin — Tmax)	270–290	°C	
Mold temperature	80–120	°C	

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Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical values.

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